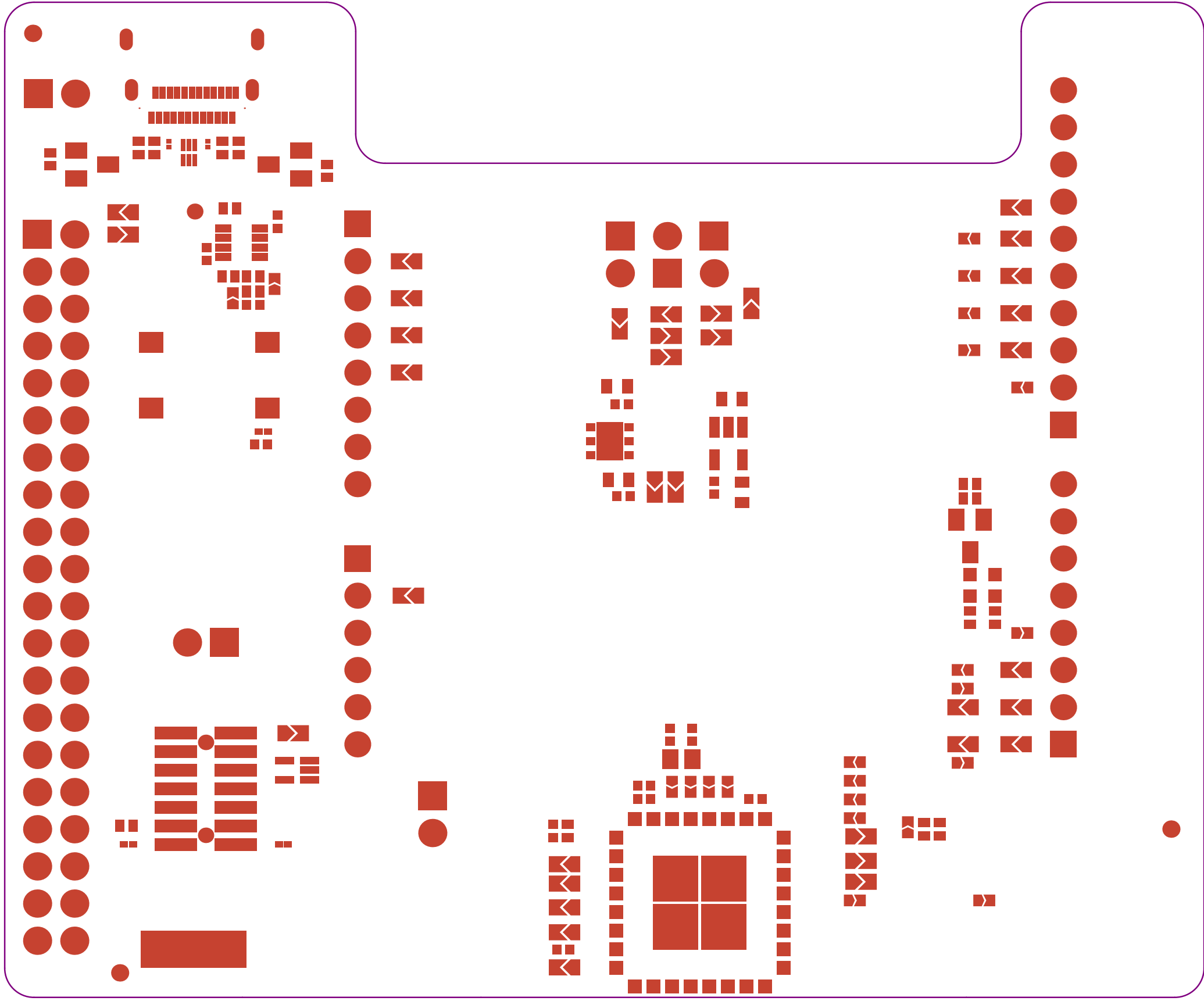

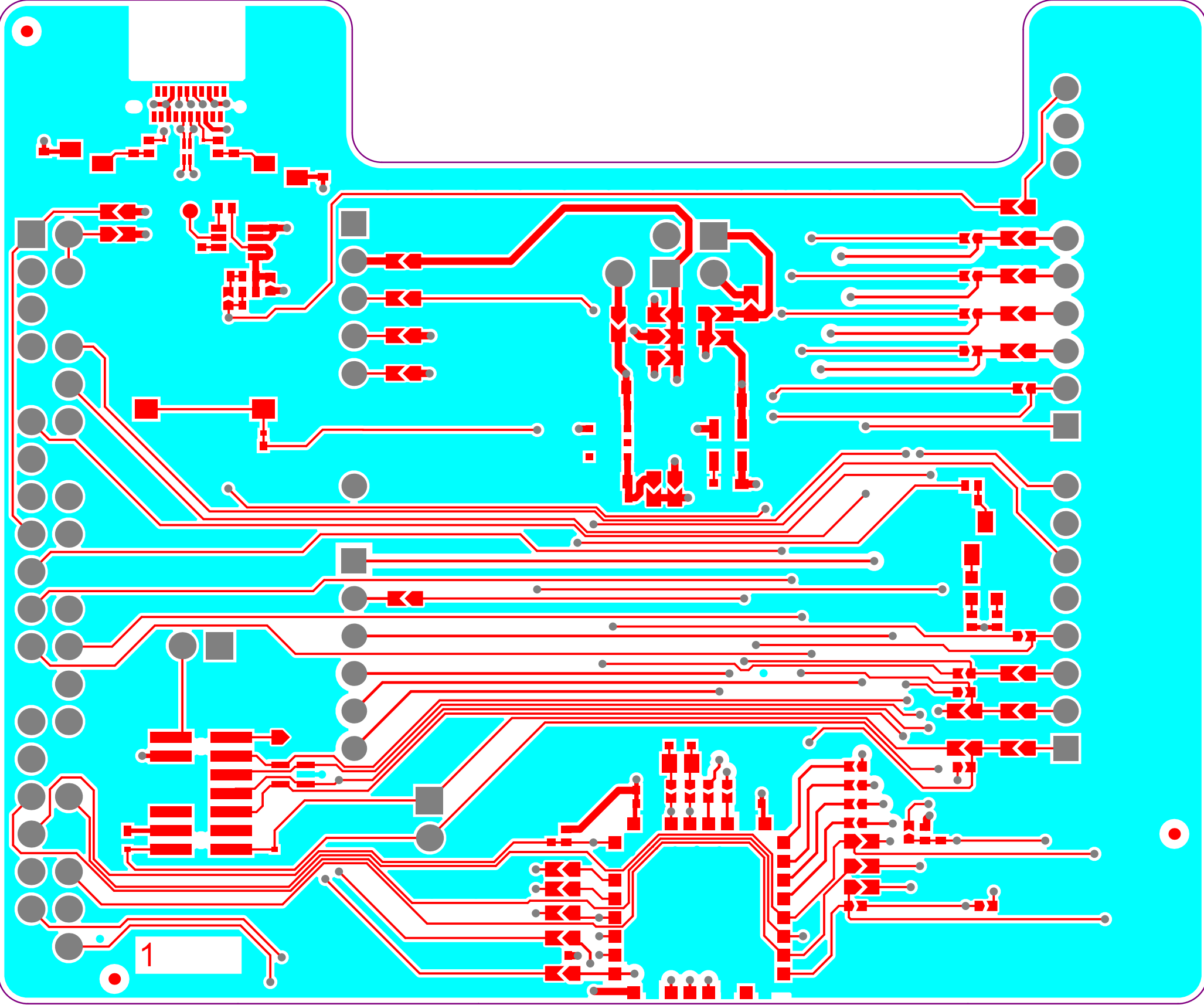


Project: X-NUCLEO-WW611M1	
Layer: Top Overlay	Gerber: .GTO
Variant: [No Variations]	Ref: MB2230
Date: 05-SEPT-24	Rev: A

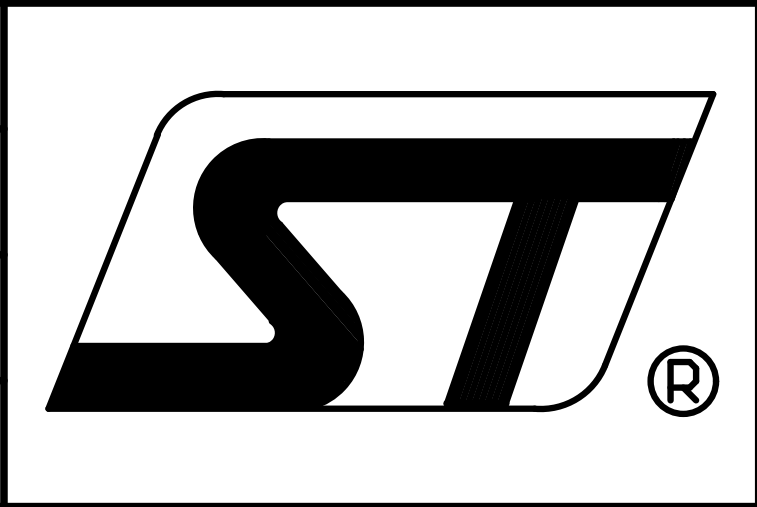


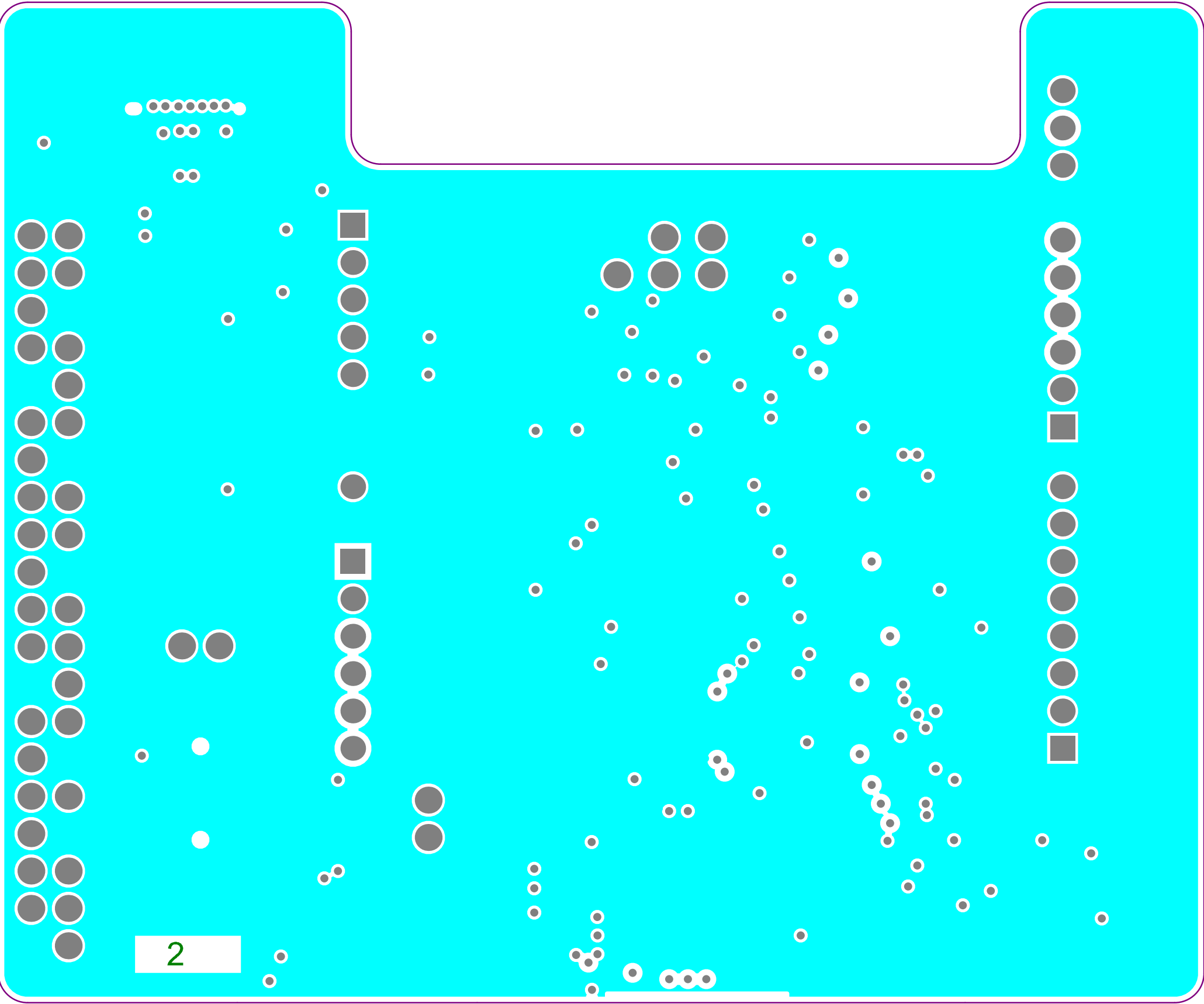



Project: X-NUCLEO-WW611M1		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB2230	
Date: 05-SEPT-24	Rev: A	

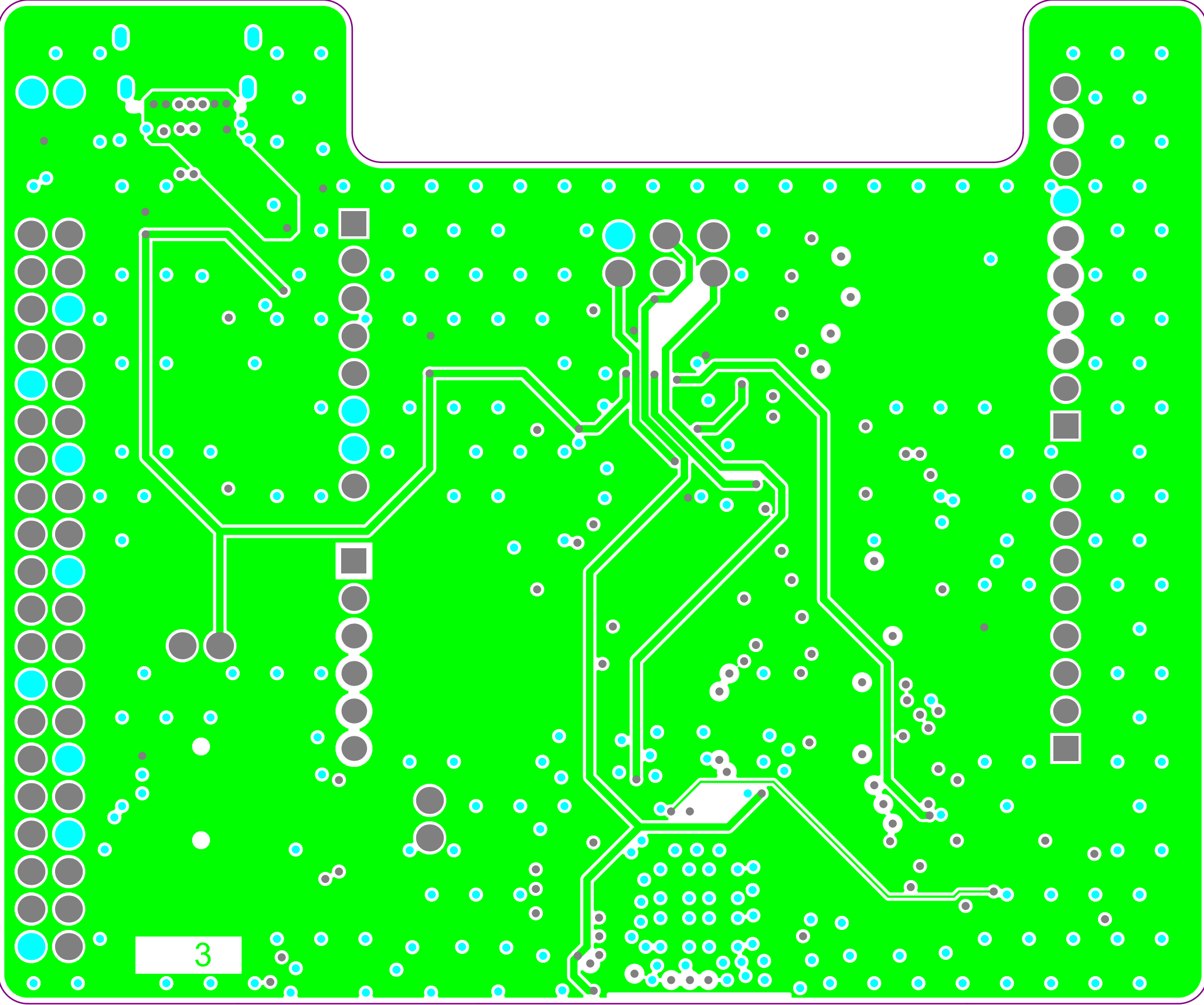


Project: X-NUCLEO-WW611M1	
Layer: Top Layer	Gerber: .GTL
Variant: [No Variations]	Ref: MB2230
Date: 05-SEPT-24	Rev: A

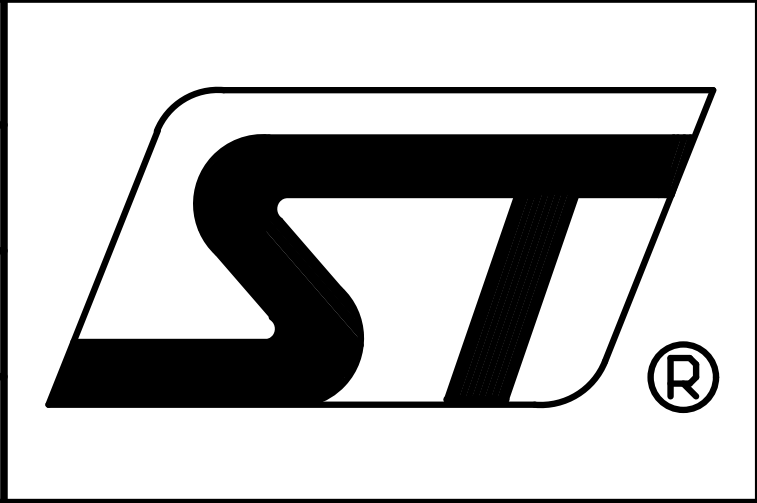


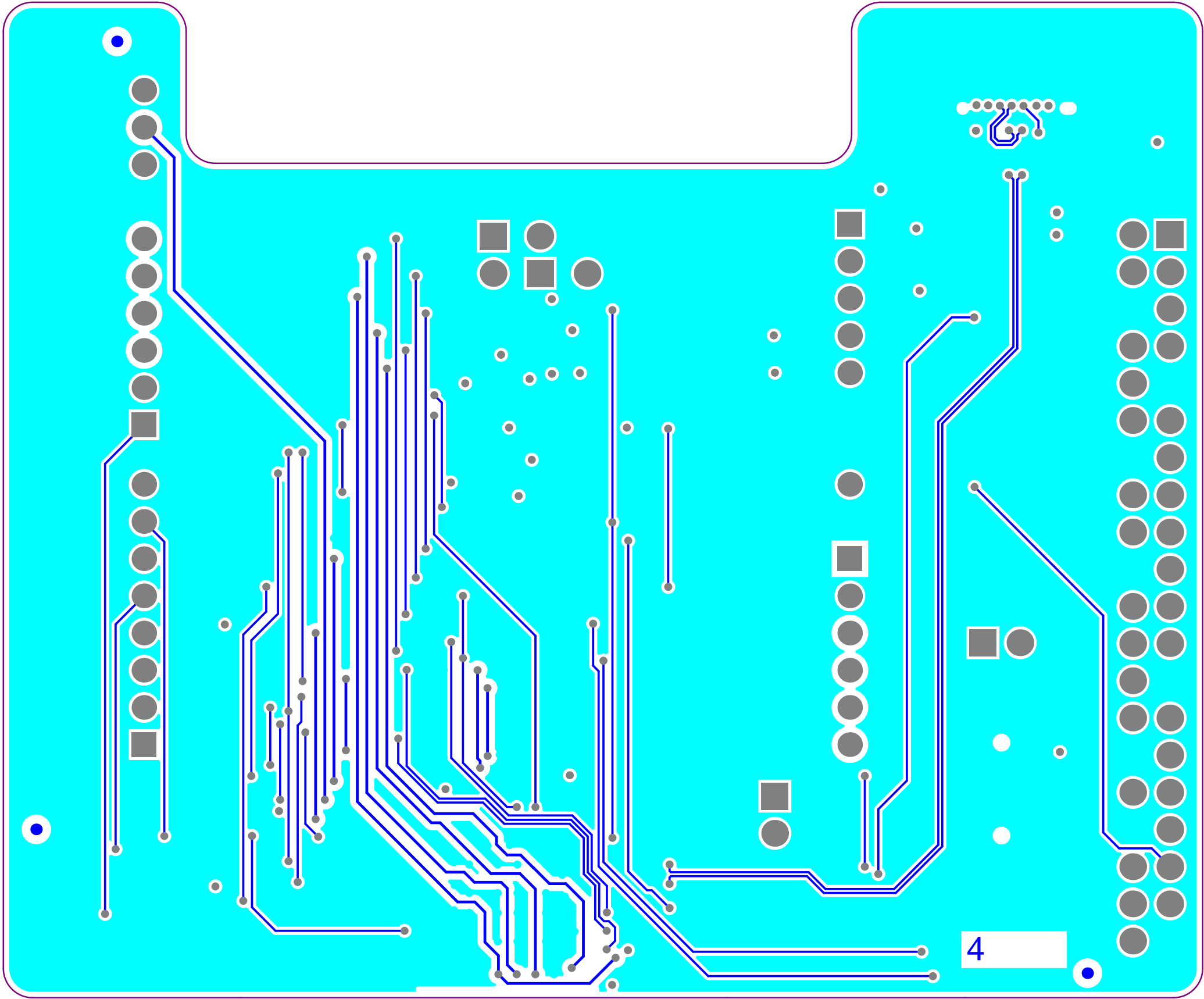



Project: X-NUCLEO-WW611M1		
Layer: Signal Layer 1	Gerber: .G1	
Variant: [No Variations]	Ref: MB2230	
Date: 05-SEPT-24	Rev: A	

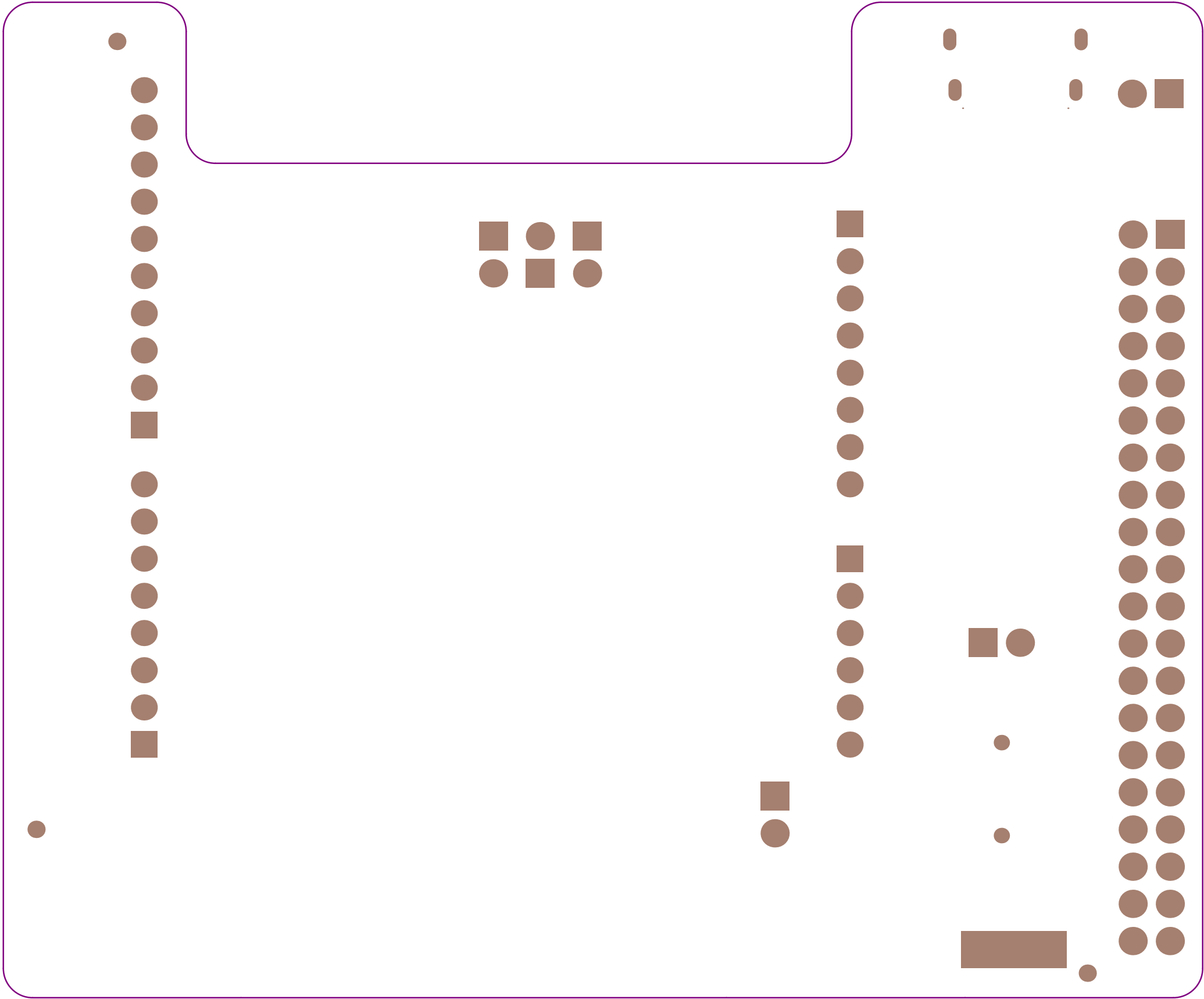


Project: X-NUCLEO-WW611M1	
Layer: Signal Layer 2	Gerber: .G2
Variant: [No Variations]	Ref: MB2230
Date: 05-SEPT-24	Rev: A





Project: X-NUCLEO-WW611M1		
Layer: Bottom Layer	Gerber: .GBL	
Variant: [No Variations]	Ref: MB2230	
Date: 05-SEPT-24	Rev: A	



Project: X-NUCLEO-WW611M1

Layer: Bottom Solder

Gerber:.GBS

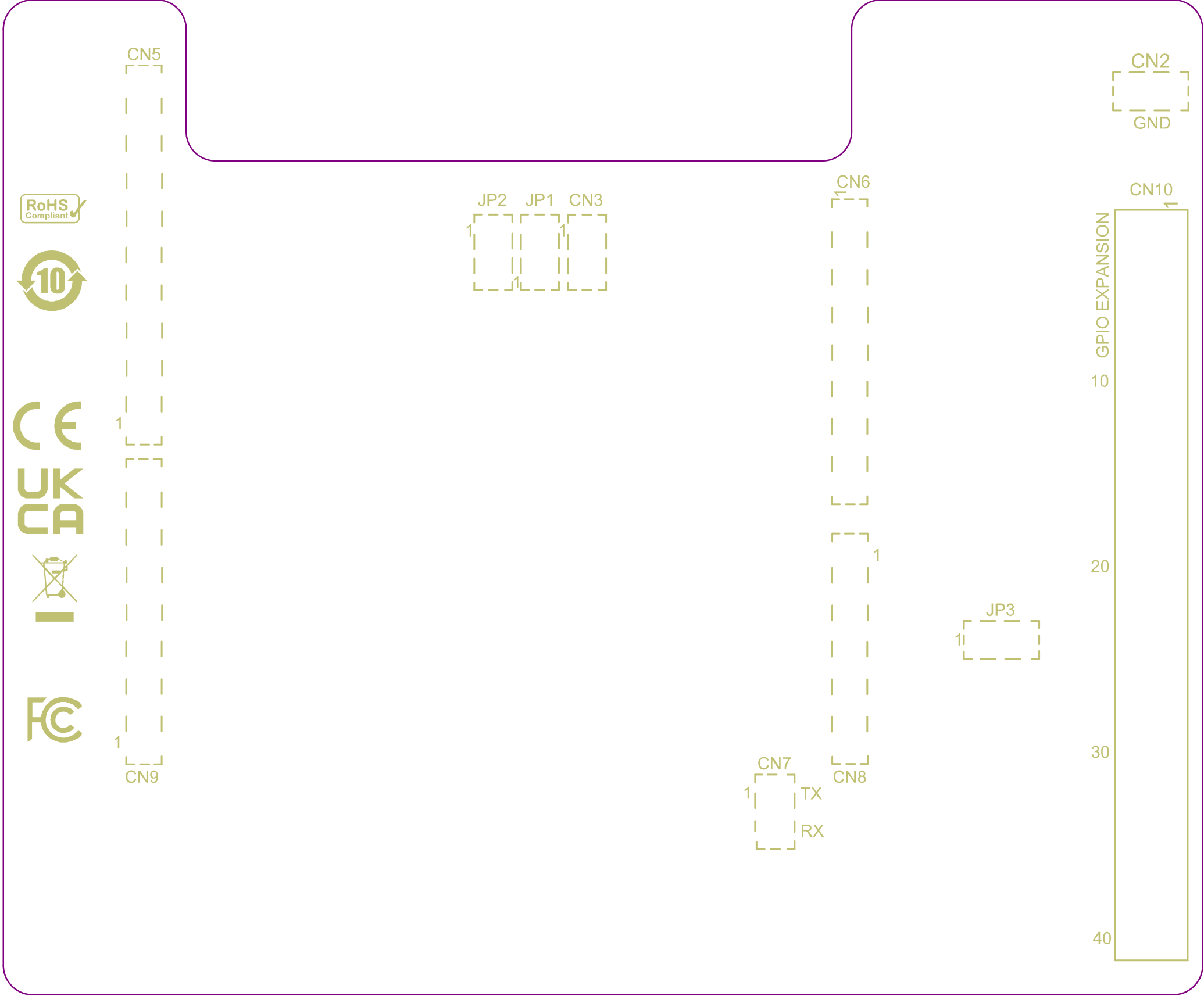
Variant: [No Variations]


Ref: MB2230

Date: 05-SEPT-24

Rev: A





Project: X-NUCLEO-WW611M1		
Layer: Bottom Overlay	Gerber:.GBO	
Variant: [No Variations]	Ref: MB2230	
Date: 05-SEPT-24	Rev: A	

« THE COMPONENTS WITH PLATED THROUGH HOLE (PTH) MAY BE WELDED (CABLED) IN "PIN-IN-PASTE" MODE (IF NECESSARY) »

PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :

FR-4

□ TG-170

☒ TG-150

□ TG-140

N/A

☐ GREEN

☐ WHITE

☐ RED

☒ BLUE

☒ WHITE

☐ YELLOW

☐ BLACK

☐ Blue ink PANTONE 2955

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

☐ NO

☒ YES (SEE PPTX FILE)

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.
SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

**Plating type :

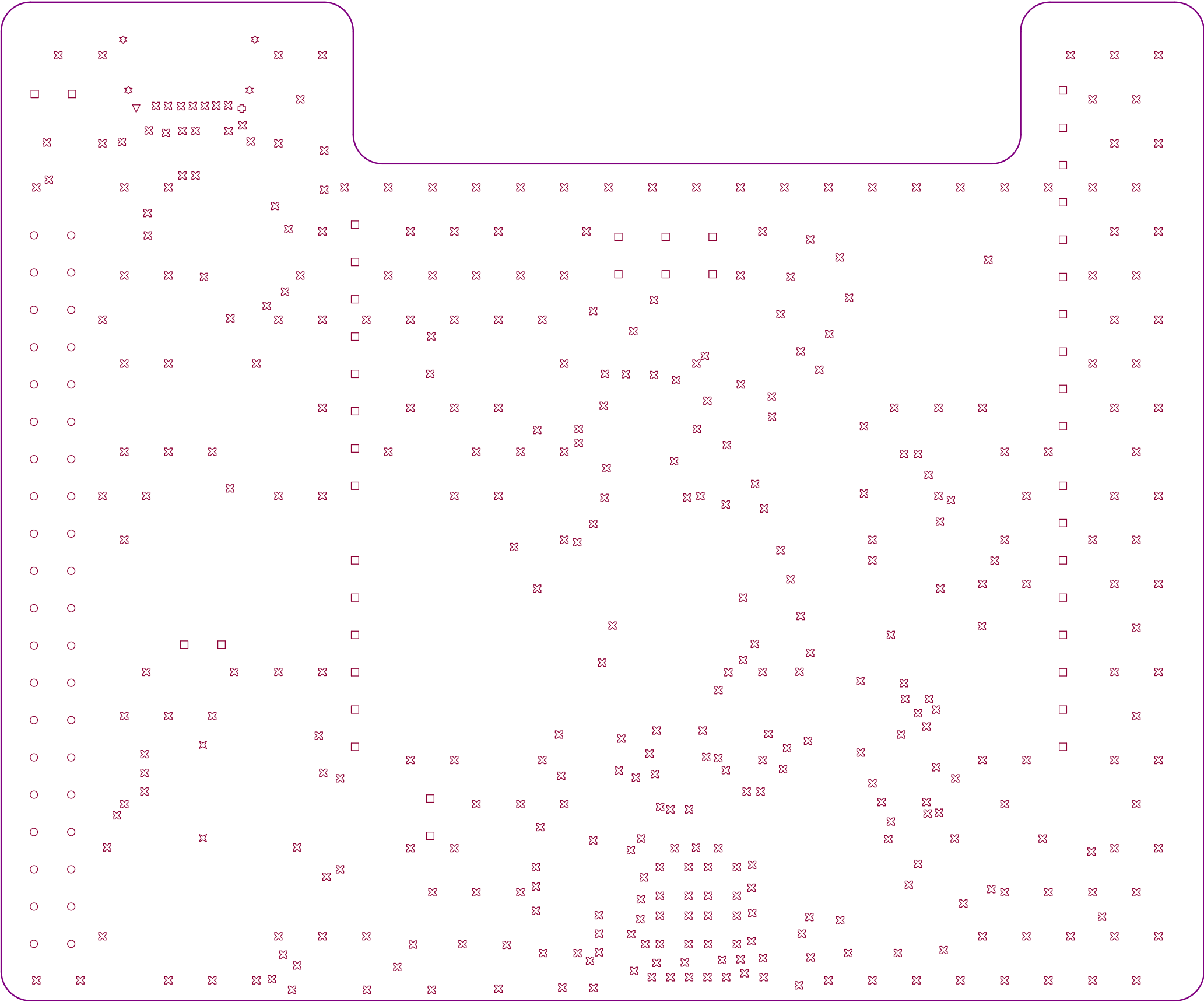
lead Gold

PCB : TYPE 3

ASPECT-RATIO, AXE Z :
6:1 to 8:1
LEVEL "B"

MINIMUM PARAMETERS

DEFAULT
TRACKS : 0.150mm
GAPS : 0.150mm



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.015mm	3.5	
1	Top Layer	CF-004	0.035mm		
	Dielectric 1	PP-3313 RC55 x2	0.108mm	3.8	
2	Signal Layer 1	CF-004	0.035mm		
	Dielectric 2	Core-IT180A	1.134mm	5.1	
3	Signal Layer 2	CF-004	0.035mm		
	Dielectric 3	PP-3313 RC55 x2	0.108mm	3.8	
4	Bottom Layer	CF-004	0.035mm		
	Bottom Solder	SM-001	0.015mm	3.5	
	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Hole Length	Routed Path Length
⊗	398	0.300mm (11.81mil)	PTH	Round	Top Layer - Bottom Layer	Via	-	-
⊛	4	0.500mm (19.69mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	1.100mm (43.31mil)	0.600mm (23.62mil)
⊕	1	0.650mm (25.59mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
▽	1	0.650mm (25.59mil)	NPTH	Slot	Top Layer - Bottom Layer	Pad	0.950mm (37.40mil)	0.300mm (11.81mil)
⊗	2	0.970mm (38.19mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
□	44	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
○	40	1.100mm (43.31mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
	490 Total							

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Project: X-NUCLEO-WW611M1

Layer: Drill Drawing

Gerber: .DRL

Variant: [No Variations]

Ref: MB2230

Date: 05-SEPT-24

Rev: A

